

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Wolfgang Hetzel et al. Examiner: James M. Mitchell
Serial No.: 10/577,173 Group Art Unit: 2813
Filed: April 26, 2006 Docket No.: I441.141.101/QIM4346
Title: SEMICONDUCTOR DEVICE WITH PLASTIC PACKAGE MOLDING
COMPOUND, SEMICONDUCTOR CHIP AND LEADFRAME AND
METHOD FOR PRODUCING SAME

AMENDMENT AND RESPONSE TO EX PARTE QUAYLE

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

This Response is in reply to the Ex Parte Quayle Office Action mailed January 19, 2011.
Please amend the above-identified patent application as follows: